

Featuring Andon's Unique SenstacTM Contact

PYXALIS							
PYXALIS Model Number	Andon Part Number Replace "XXX" with Terminal Type	Terminal Type			Pin Ø [in]	Figure Number	Page Number
		Thru-Hole	Surface Mount	Rollerball®			
GIGAPYX4600	10-43-05-520-XXX-R27-L14	274UM	-	RB338UM	-	4	2
GIGAPYX 46M	10-43-05-520-XXX-R27-L14	274UM	-	RB338K	-	4	2
HDPYX 130	17-10-01-100-XXX-R27-L14 (w/adapter)	437T	329T	-	-	3	2
	OR 685-100-XX-XXX-R27-L14-1 (w/cover & screws)	TH-491	SM-500	-	-	4	2
HDPYX 160	17-10-01-100-XXX-R27-L14 (w/adapter)	437T	329T	-	-	3	2
	OR 685-100-XX-XXX-R27-L14-1 (w/cover & screws)	TH-491	SM-500	-	-	5	2
HDPYX1600-G	694-292A-xx-xxx-R27-L14-1	TH-491	SM-500	SM-RB593	-	8	3
HDPYX 230	17-12-08-104-XXX-R27-L14 (w/adapter)	437T	329T	-	-	2	1
	OR 685-104-XX-XXX-R27-L14-1 (w/cover & screws)	TH-491	SM-500	-	-	6	2
HDPYX 300	575-13-89-077-XXX-R27-L14	01M	93M	RB338K	-	1	1
HDPYX330-C	694-292-xx-xxx-R27-L14-1	TH-491	SM-500	SM-RB593	-	7	3

See last page for other mounting types including low profile options.

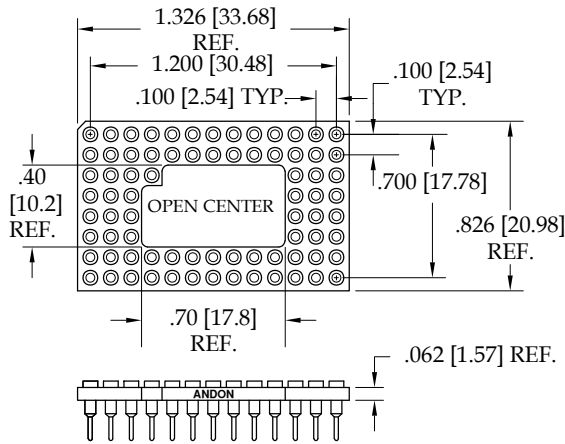


Fig. 01 77 Pins

Thru-Hole: 575-13-89-077-01M-R27-L14
 Surface Mount: 575-13-89-077-93M-R27-L14
 Rollerball® : 575-13-89-077-RB338K-R27-L14

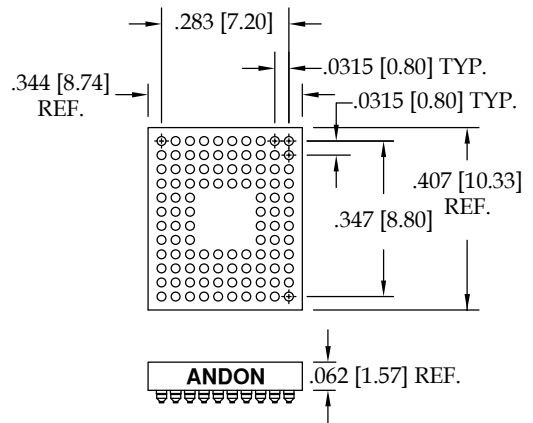


Fig. 02 104 Pins

Thru-Hole: 17-12-08-104-437T-R27-L14
 Surface Mount: 17-12-08-104-329T-R27-L14
 Adapter: 17-12-08-104-321-G10-L14

Pyxalis Continued Image Sensor Socket Footprints

Units: in [mm]

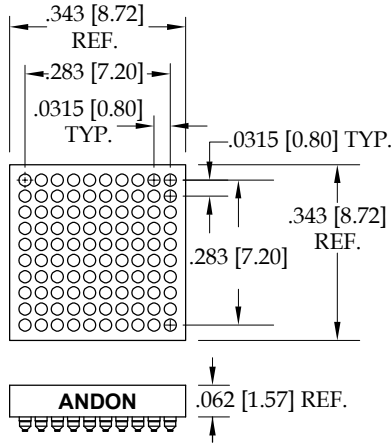


Fig. 03 100 Pins
Thru-Hole: 17-10-01-100-437T-R27-L14
Surface Mount: 17-10-01-100-329T-R27-L14
Adapter: 17-10-01-100-321-G10-L14

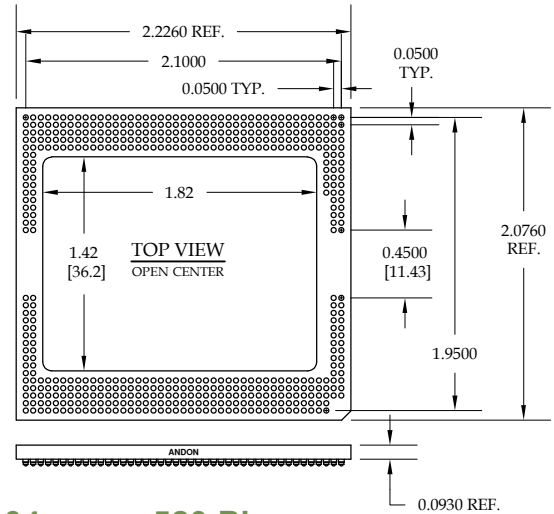
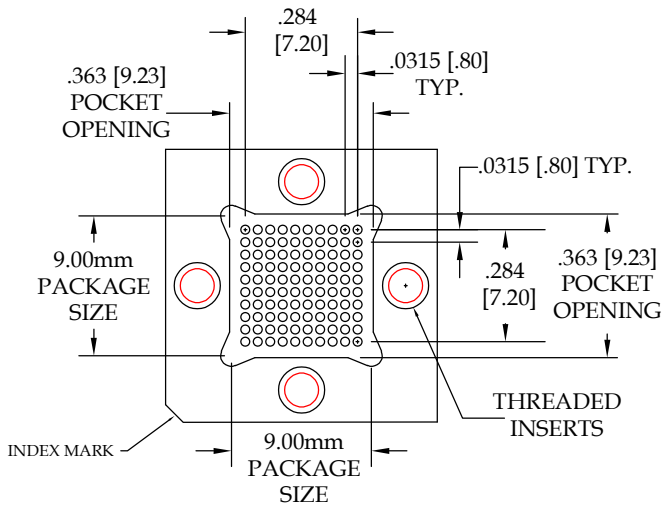
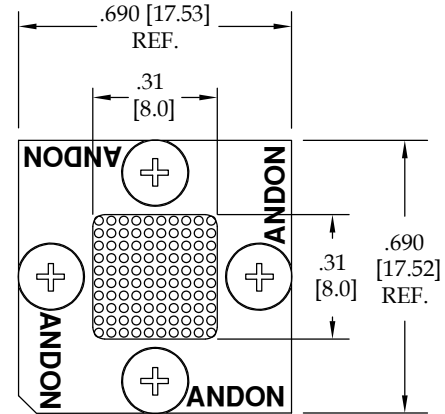


Fig. 04 520 Pins
Thru-Hole: 10-43-05-520-274UM-R27-L14
Surface Mount: N/A
Rollerball® : 10-43-05-520-RB338UM-R27-L14



GUIDE & BASE SHOWN



COVER & HARDWARE SHOWN

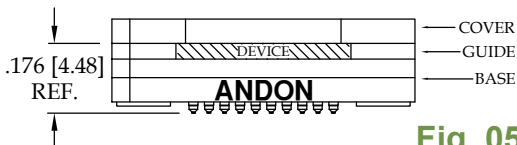
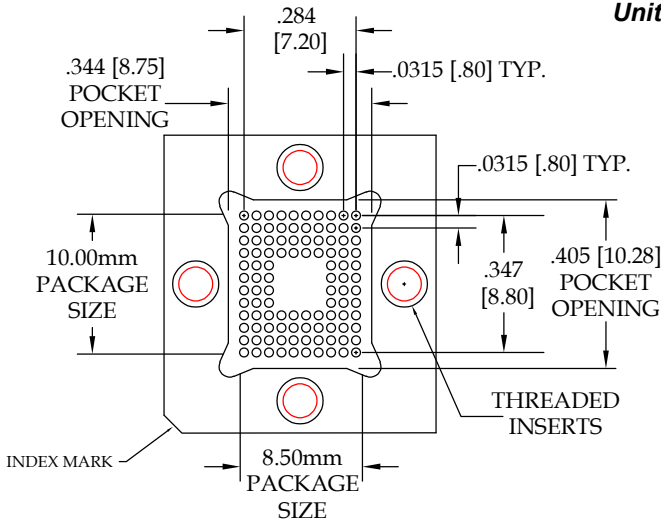


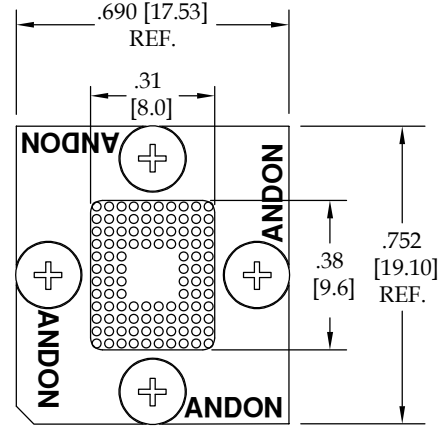
Fig. 05 100 Pins
Thru-Hole: 685-100-TH-491-R27-L14-1
Surface Mount: 685-100-SM-500-R27-L14-1

Pyxalis Continued Image Sensor Socket Footprints

Units: in [mm]



GUIDE & BASE SHOWN



COVER & HARDWARE SHOWN

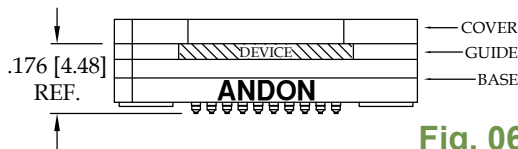
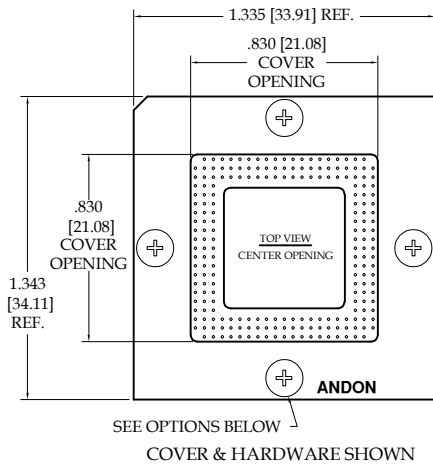
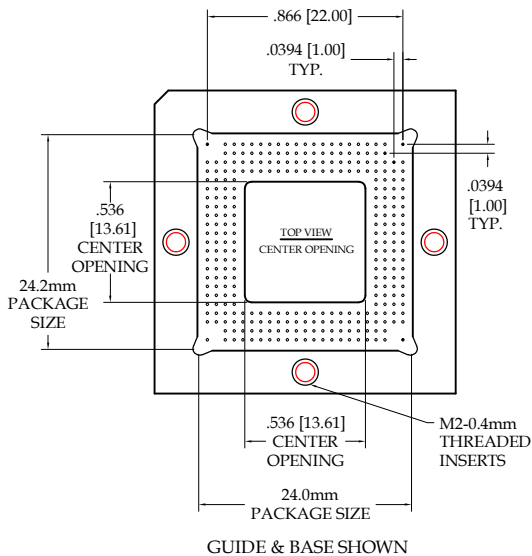


Fig. 06 104 Pins
Thru-Hole: 685-104-TH-491-R27-L14-1
Surface Mount: 685-104-SM-500-R27-L14-1



SEE OPTIONS BELOW
COVER & HARDWARE SHOWN



GUIDE & BASE SHOWN

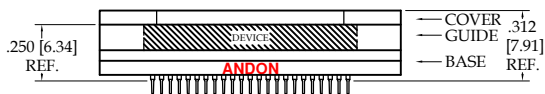


Fig. 07 292 Pins
Thru-Hole: 694-292-TH-491-R27-L14-1
Surface Mount: 694-292-SM-500-R27-L14-1
Rollerball® : 694-292-SM-RB593-R27-L14-1

Pyxalis *Continued* Image Sensor Socket Footprints Units: in [mm]

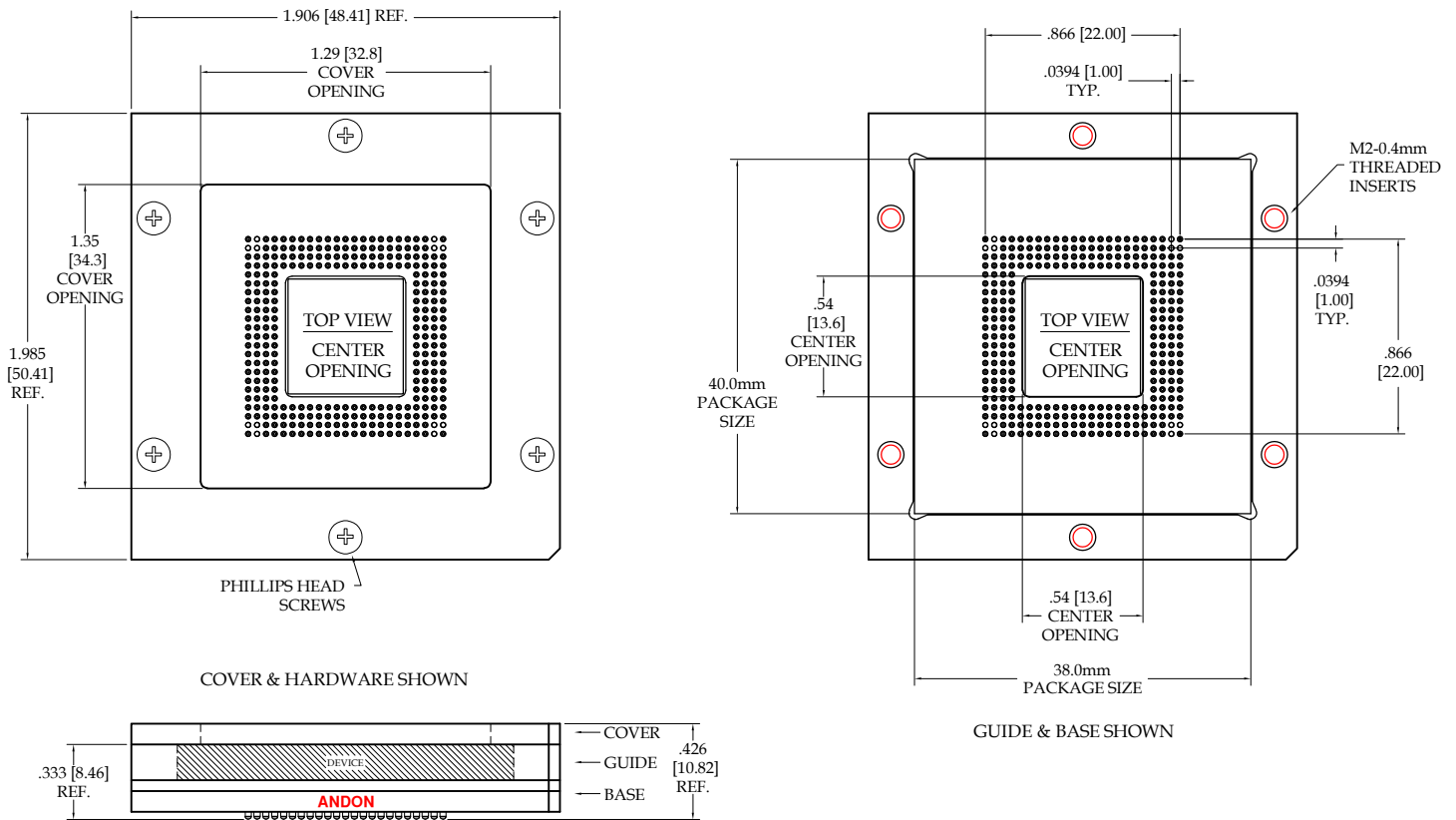


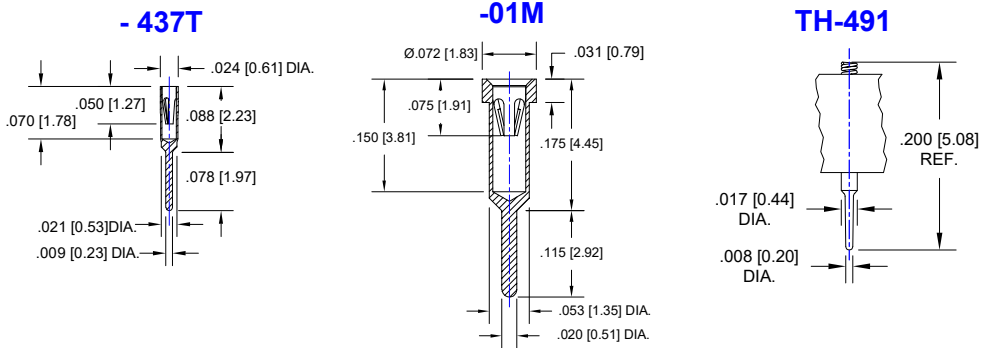
Fig. 08 292 Pins
Thru-Hole: 694-292A-TH-491-R27-L14-1
Surface Mount: 694-292A-SM-500-R27-L14-1
Rollerball® : 694-292A-SM-RB593-R27-L14-1

Pyxalis Continued

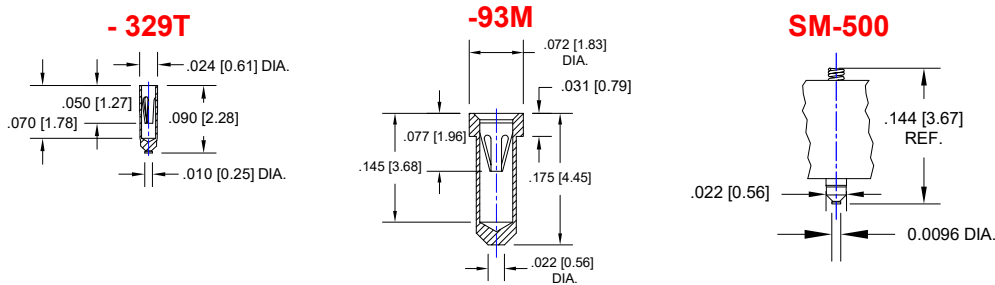
Image Sensor Terminal Options

Units: in [mm]

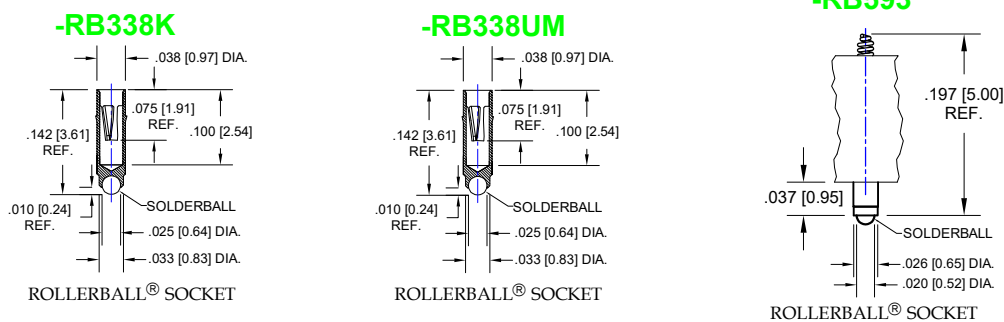
THRU HOLE OPTION



SURFACE MOUNT OPTION



ROLLERBALL® OPTION



Terminal Acceptance and Forces

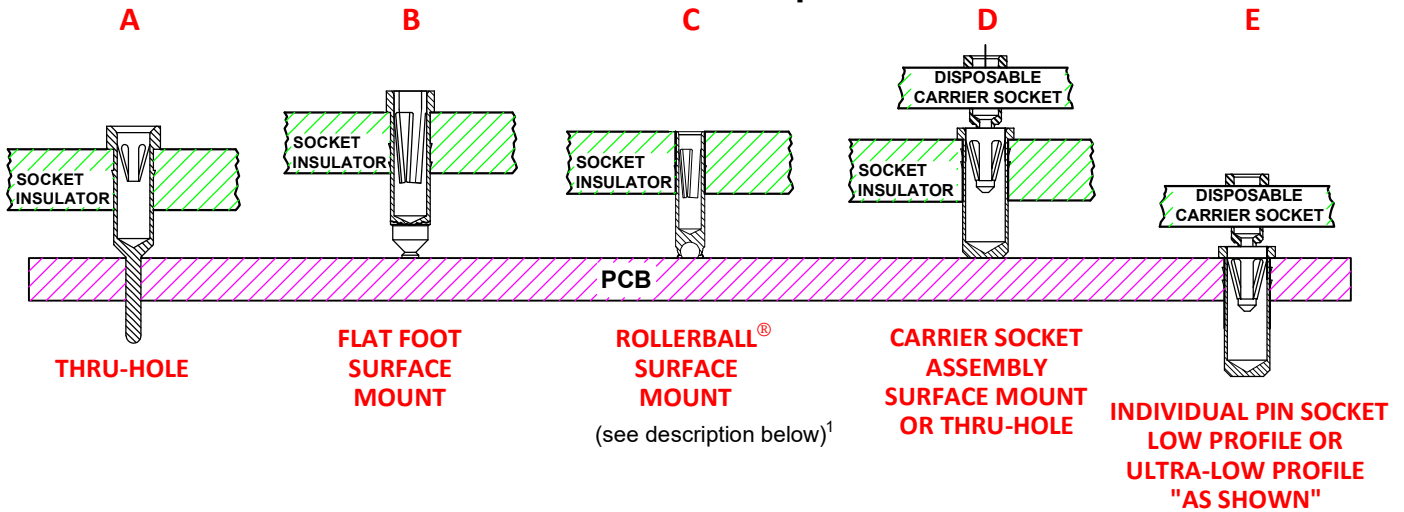
Thru Hole Socket Terminals				Surface Mount Socket Terminals			
Thru Hole Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force	Surface Mount Terminal	Accepts Pin Diameter	Insertion Force	Withdrawal Force
-437T	Ø.010 [Ø0.25]	1.0 oz Avg.	0.3 oz Min	-329T	Ø.010 [Ø0.25]	1.0 oz Avg.	0.3 oz Min
-01M	Ø.018 [Ø0.46]	1.6 oz Avg.	0.5 oz Min	-93M	Ø.018 [Ø0.46]	1.6 oz Avg.	0.5 oz Min
-274UM	Ø.015 [Ø0.38]	2.1 oz Avg.	0.5 oz Min	-281UM	Ø.015 [Ø0.38]	2.1 oz Avg.	0.5 oz Min
				-RB338K	Ø.018 [Ø0.46]	1.60 oz Max	0.50 oz Min
				-RB338UM	Ø.015 [Ø0.38]	2.1 oz Avg.	0.5 oz Min
				-RB593	-	-	-

Technical Information

Plating: RoHS COMPLIANT
R27 TERMINAL: GOLD / CONTACT: GOLD
R29 TERMINAL: MATTE TIN / CONTACT: GOLD
R32 TERMINAL: MATTE TIN / CONTACT: TIN
 OTHER PLATINGS AVAILABLE

Material:
 Insulator: Hi-Temp UL 94V-0
 Terminal: Brass, per ASTM-B16
 Contact: BeCu, Per ASTM-B194

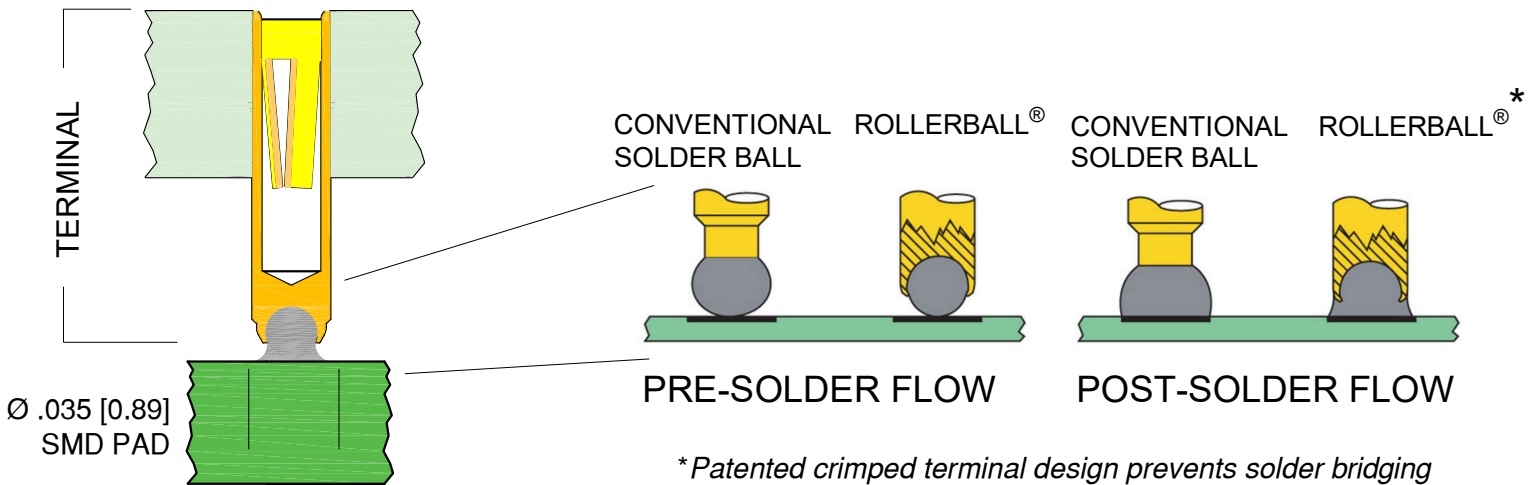
Socket Terminal Options



¹Andon's patented Rollerball[®] socket terminal option provides more accurate soldering, a stronger connection, and improved electrical connectivity - especially under shock and vibration - than other solder ball terminal designs. Better yet, it can enable you to avoid expensive rework and scrap - especially with larger PCBs where coplanarity is an inherent challenge.

The bottom of these terminals has a radiused hole, to prevent gas entrapment. The terminal is crimped over the solder ball beyond its hemisphere, encapsulating it - leaving just enough of the solder ball exposed to provide sufficient solder without the solder bridging common in conventional solder ball terminal designs.

With this unique design, the critical distance between the terminal and the PC board pad is typically reduced from .036"-.040" to .018"-.022". As such, the solder becomes part of the "anchor" cross-section - providing additional mechanical strength to the connection, as well as improved electrical connectivity. Because it also provides controlled dispersion of solder, this encapsulated solder ball reduces the risk of solder bridging inherent in conventional solder ball terminal designs.



For fast, accurate placement of SIP sockets and ultra-low profile terminals

Phase 1:
Receive Carrier Assemblies designed to your pin layout.



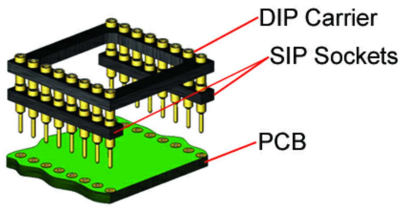
Phase 2:
Place carrier assemblies onto PCB; run through your soldering process.



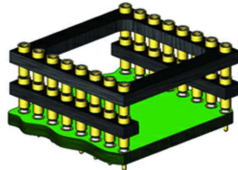
Phase 3:
Remove carrier and plug in your device; discard carrier.

DIP

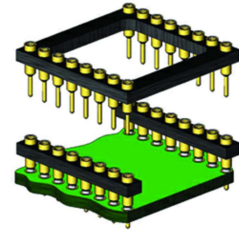
Before Soldering



During Soldering

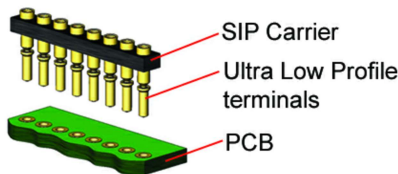


After Soldering

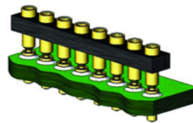


ULTRA-LOW PROFILE SIP

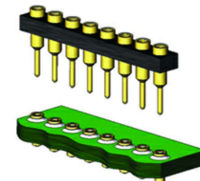
Before Soldering



During Soldering

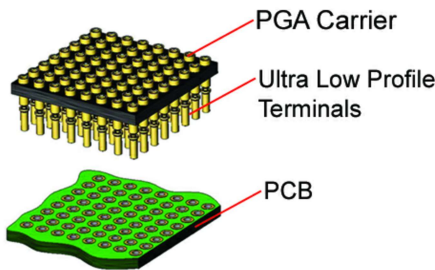


After Soldering

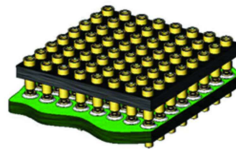


ULTRA-LOW PROFILE PGA

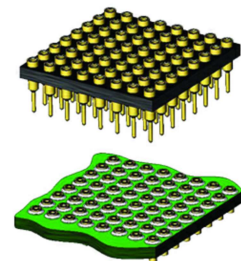
Before Soldering



During Soldering

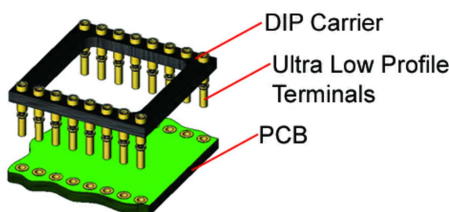


After Soldering

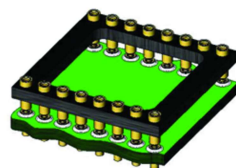


ULTRA LOW PROFILE DIP

Before Soldering



During Soldering



After Soldering

